

DOCKET NO. 12980F383USO

PATENT

Receipt

2800

#14/CRR

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Sailesh Chittipeddi, et al.

COPY OF PAPERS
ORIGINALLY FILED

Serial No.: 09/467,253

Filed: December 20, 1999

For: WIRE BONDING METHOD FOR COPPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

Group No.: 2823

Examiner: Estrada, Michelle

RECEIVED
MAR 14 2002
TC 2800 MAIL ROOM

Commissioner for Patents
Washington, D. C. 20231

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231, on 1-29-02 (Date)
Elizabeth Schumacher
(Printed or typed name of person signing the certificate)
Elizabeth Schumacher
(Signature of the person signing the certificate)

Sir:

REQUEST FOR CORRECTED OFFICIAL FILING RECEIPT

Attached is a copy of the Official Filing Receipt received from the Patent and Trademark Office in this application.

Please amend the Attorney Docket No. on the Official Filing Receipt to: CHITTIPEDDI 59-108.

Respectfully submitted,

HITT GAINES & BOISBRUN, P.C.

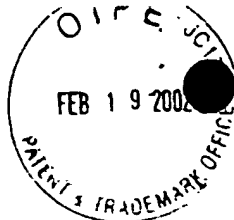
Charles W. Gaines

Charles W. Gaines
Registration No. 36,804

Date: 1/29/02

Hitt Gaines & Boisbrun, P.C.
P.O. Box 832570
Richardson, Texas 75083
(972) 480-8800

FILING RECEIPT

UNITED STATES DEPARTMENT OF COMMERCE
Patent and Trademark Office
ASSISTANT SECRETARY AND COMMISSIONER
OF PATENTS AND TRADEMARKS
Washington, D.C. 20231

| APPLICATION NUMBER | FILING DATE | GRP ART UNIT | FIL FEE REC'D | ATTORNEY DOCKET NO. | DRWGS | TOT CL | IND CL |
|--------------------|-------------|--------------|---------------|---------------------|-------|--------|--------|
| 09/467,253 | 12/20/99 | 2811 | \$760.00 | 374 12980F385USO | 5 | 20 | 3 |

DARBY & DARBY
805 THIRD AVENUE
NEW YORK NY 1002227964/
HITTAILESS BISHOP

CHITTIPEDDI 59.108

Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts of Application" ("Missing Parts Notice") in this application, please submit any corrections to this Filing Receipt with your reply to the "Missing Parts Notice." When the PTO processes the reply to the "Missing Parts Notice," the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s) SAILESH CHITTIPEDDI, ALLENTOWN, PA; SAILESH MANSINH
MERCHANT, ORLANDO, FL.

IF REQUIRED, FOREIGN FILING LICENSE GRANTED 02/04/00

TITLE

WIRE BONDING METHOD FOR COOPER INTERCONNECTS
IN SEMICONDUCTOR DEVICES

PRELIMINARY CLASS: 257

COPY OF PAPERS
ORIGINALLY FILEDRECEIVED
MAR 14 2002
TC 2800 MAIL ROOMComputer TCR
D&D Entry TCR
Looseleaf _____
Folder TCR
Card _____
Letter _____
Foreign Flg. _____

DATA ENTRY BY: COWAN, ANNETTE

TEAM: 01 DATE: 02/04/00



(See reverse for new important information)